

***THS1408/5691 EVM for the
THS14xx and THS56xx DAC
Families***

User's Guide

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About This Manual

The purpose of this user's guide is to serve as a reference manual for the THS1408 14-bit ADC, analog-to-digital converter module (EVM). This document provides information to assist hardware and software engineers in application development.

How to Use This Manual

- Chapter 1 – Overview
- Chapter 2 – Physical Description
- Chapter 3 – Circuit Description

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This book may contain cautions and warnings.

This is an example of a caution statement.

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A warning statement describes a situation that could potentially cause harm to you.

The information in a caution or a warning is provided for your protection. Please read each caution and warning carefully.



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Overview

This chapter presents a general overview of the THS1408_5691EVM evaluation module (EVM), and describes some of the factors that must be considered in using the module.

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1.1 Purpose

The THS1408_5691EVM evaluation module (EVM) provides a platform for evaluating the THS14XX analog-to-digital converter (ADC) and the THS56XX digital-to-analog converter (DAC) under various signal, reference, and supply conditions.

Note:

The EVM in its current implementation supports only the THS14XX device family and associated circuitry. Support for the THS56XX family will become available at a later date. As a result of this, only the operation of the THS14XX and its associated circuitry will be described in this user's guide.

1.2 EVM Basic Functions

Analog input to the ADC is provided via two external SMB connectors. This input can be configured onboard to be true differential or single-ended transformer-coupled to the input of the device.

The EVM provides an external SMB connection for ADC clock input. This can be configured to be either ac- or dc-coupled. A site provided on the board for a crystal oscillator to perform this function can be populated if required. Further provision is made to run the ADC from a DSP timer if desired.

Output from the EVM takes place via two 80-pin daughtercard connectors. The digital lines from the ADC are buffered before going to the daughtercard connectors. More information on these connectors can be found in the TMS320C6000 daughtercard specification.

The EVM is powered via 4-mm banana sockets. Separate input connectors are provided for the analog and digital supplies. Provision is made to supply the EVM from the motherboard via the daughtercard connectors.

The EVM has onboard logic that controls the memory mapping of the ADC within the motherboard's peripheral memory space.

1.3 Power Requirements

The EVM can be powered directly through the daughtercard connector's +3.3-V supply. Provision has also been made to allow the EVM to be powered with independent +3.3-V analog and digital supplies where ultimate performance demands.

Voltage Limits

Exceeding the +3.3-V maximum can damage EVM components. Undervoltage may cause improper operation of some or all of the EVM components

1.4 THS1408/5691EVM Operational Procedure

The THS1408_5691EVM provides a flexible means of evaluating the THS14XX in a number of modes of operation. A basic setup procedure that can be used as a board confidence check follows:

- Verify all jumper settings against the schematic jumper table:

Device	Jumper Table (connection)
THS1408	H3 pins 2–3, H5 pins 2–3, H6 pins 2–3, H7 pins 2–3, H8 pins 1–2, H9 pins 2–3, H12 pins 1–2, H13 pins 1–2

- Check that T2 is populated.
- Connect supplies to the EVM: +3.3 V on J7 and J8, and GND on J12 and J13.
- Switch power supplies on.
- Use a function generator with a 50- Ω output to apply a 5-MHz, 1.5-V offset, 3-Vp-p amplitude square-wave signal to J3.
- Use a function generator with a 50- Ω output to apply a 100-kHz, 0-V offset, 4-Vp-p amplitude sine-wave signal to J10.
- The digital pattern on the output daughtercard connector J1 should now represent a sine wave and can be monitored using a logic analyzer, or the EVM can be plugged into a motherboard and the data can be monitored using suitable software.



Physical Description

This chapter describes the physical characteristics and PCB layout of the EVM and lists the components used on the module.

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2.1 PCB Layout

The EVM is constructed on a four-layer, 100-mm (3.94 inch) × 86-mm (3.39 inch), 1.57-mm (0.062 inch) thick PCB using FR-4 material. Figures 2–1 through 2–6 show the individual layers.

Figure 2–1. Silk Top

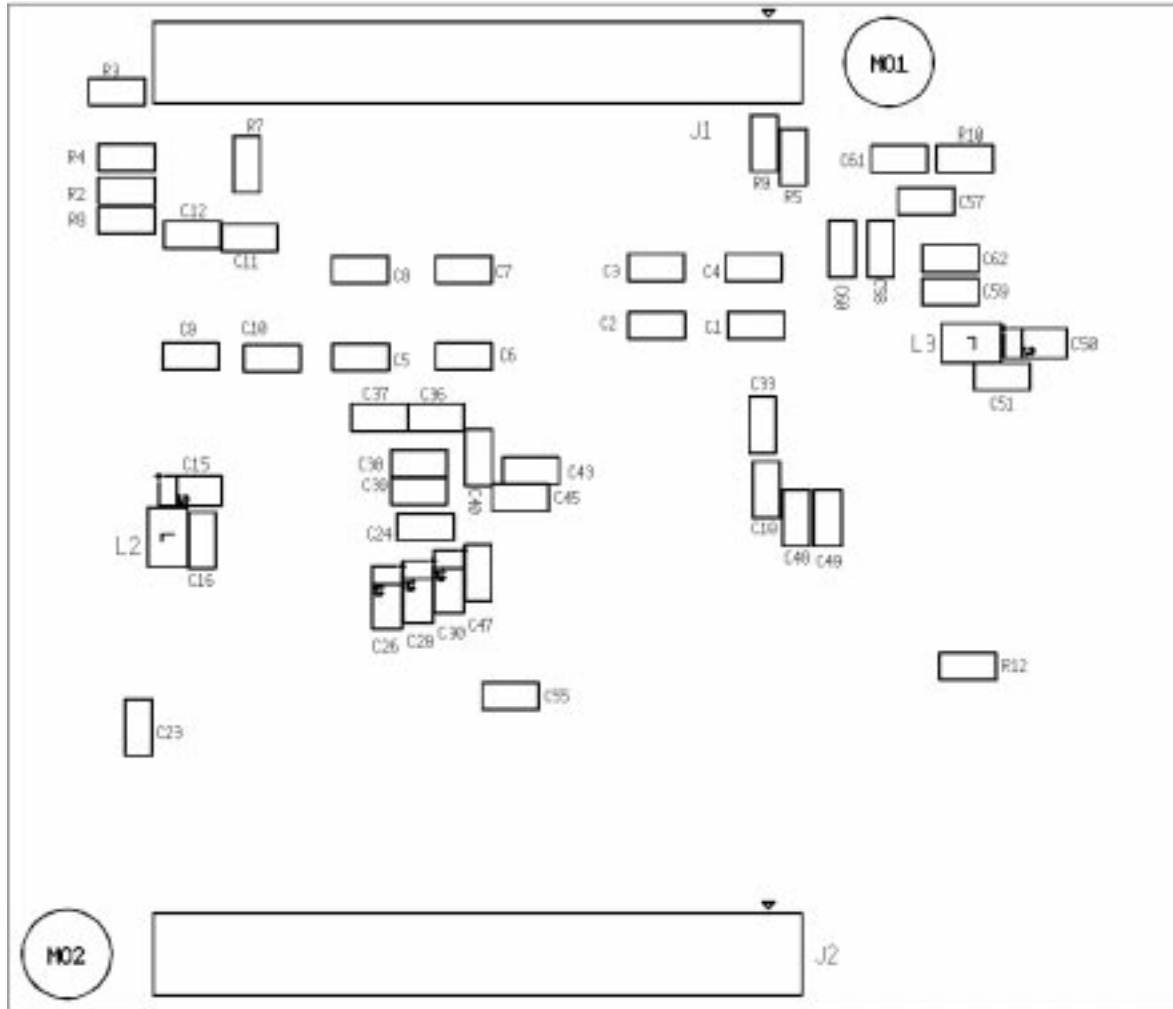


Figure 2-2. Silk Bottom

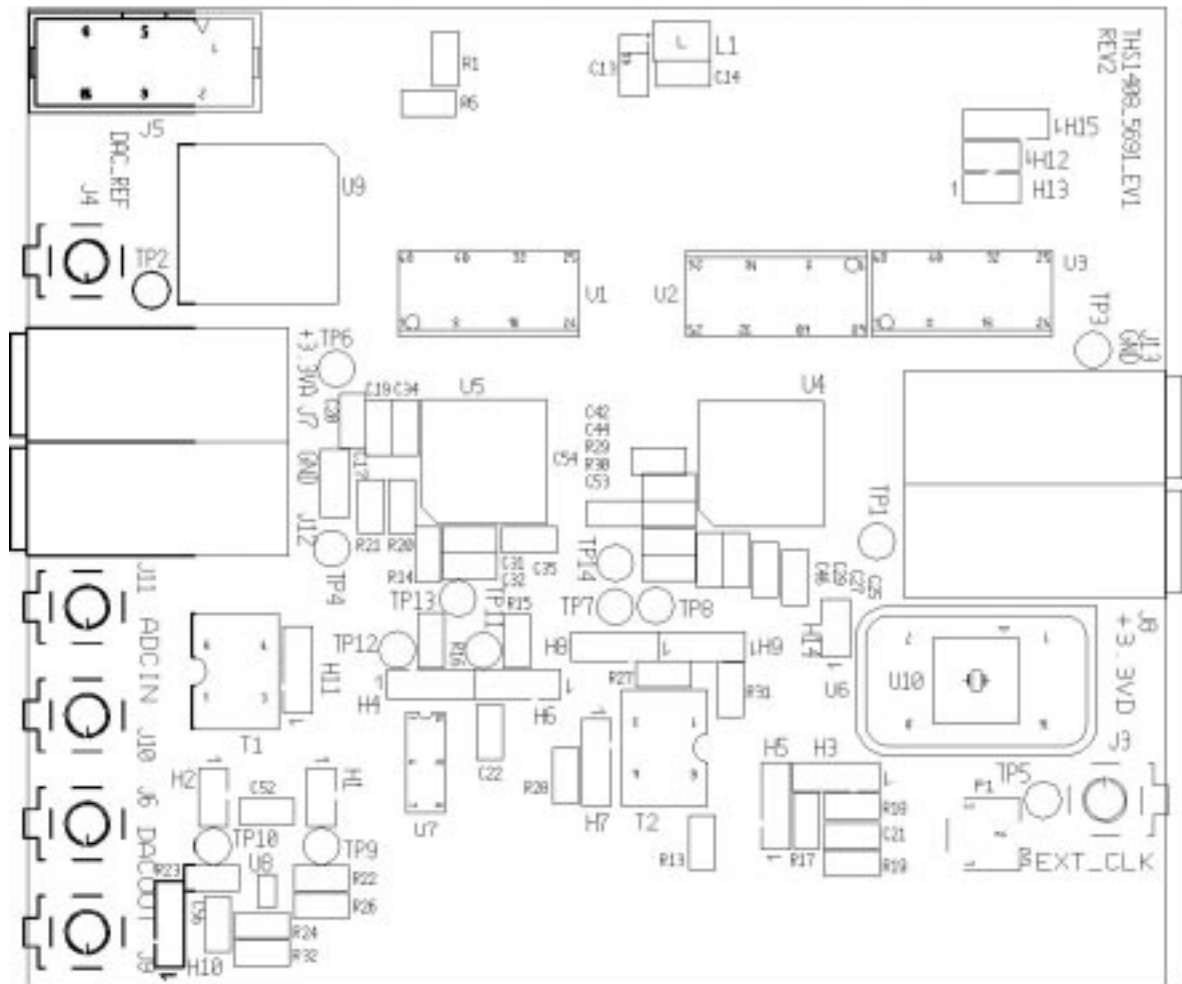


Figure 2–3. Top Layer

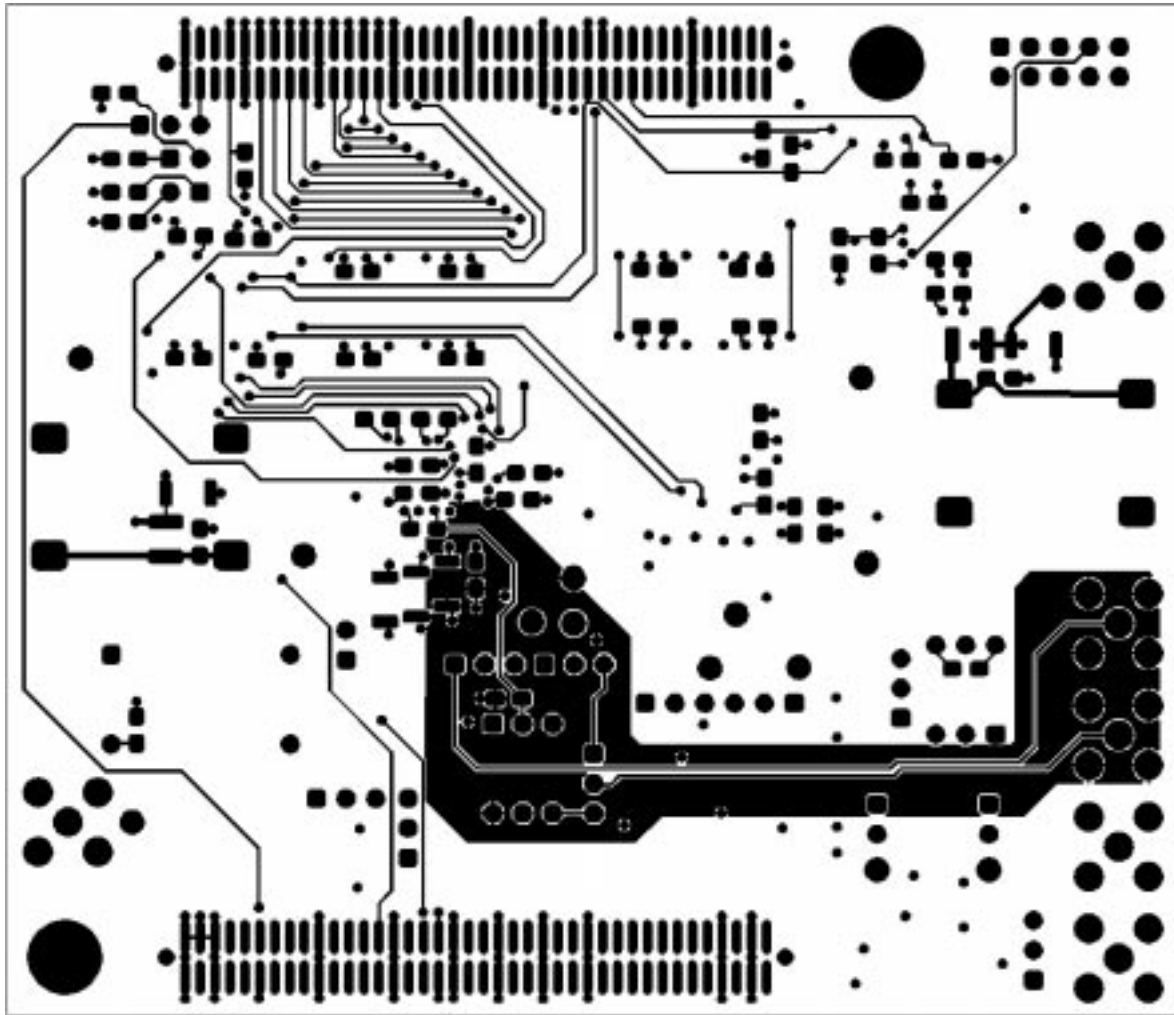


Figure 2-4. Inner Layer 1

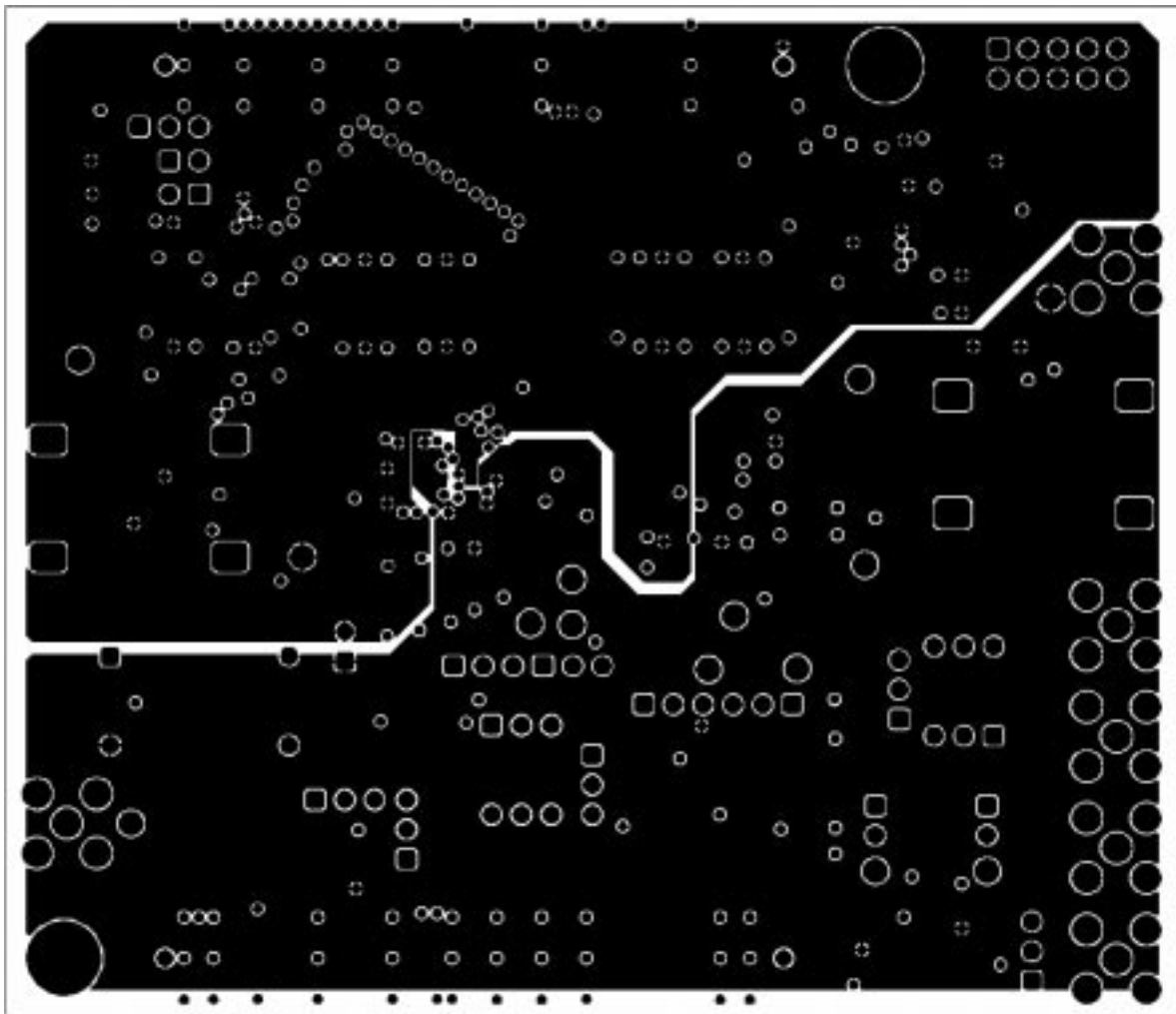


Figure 2–5. Inner Layer 2

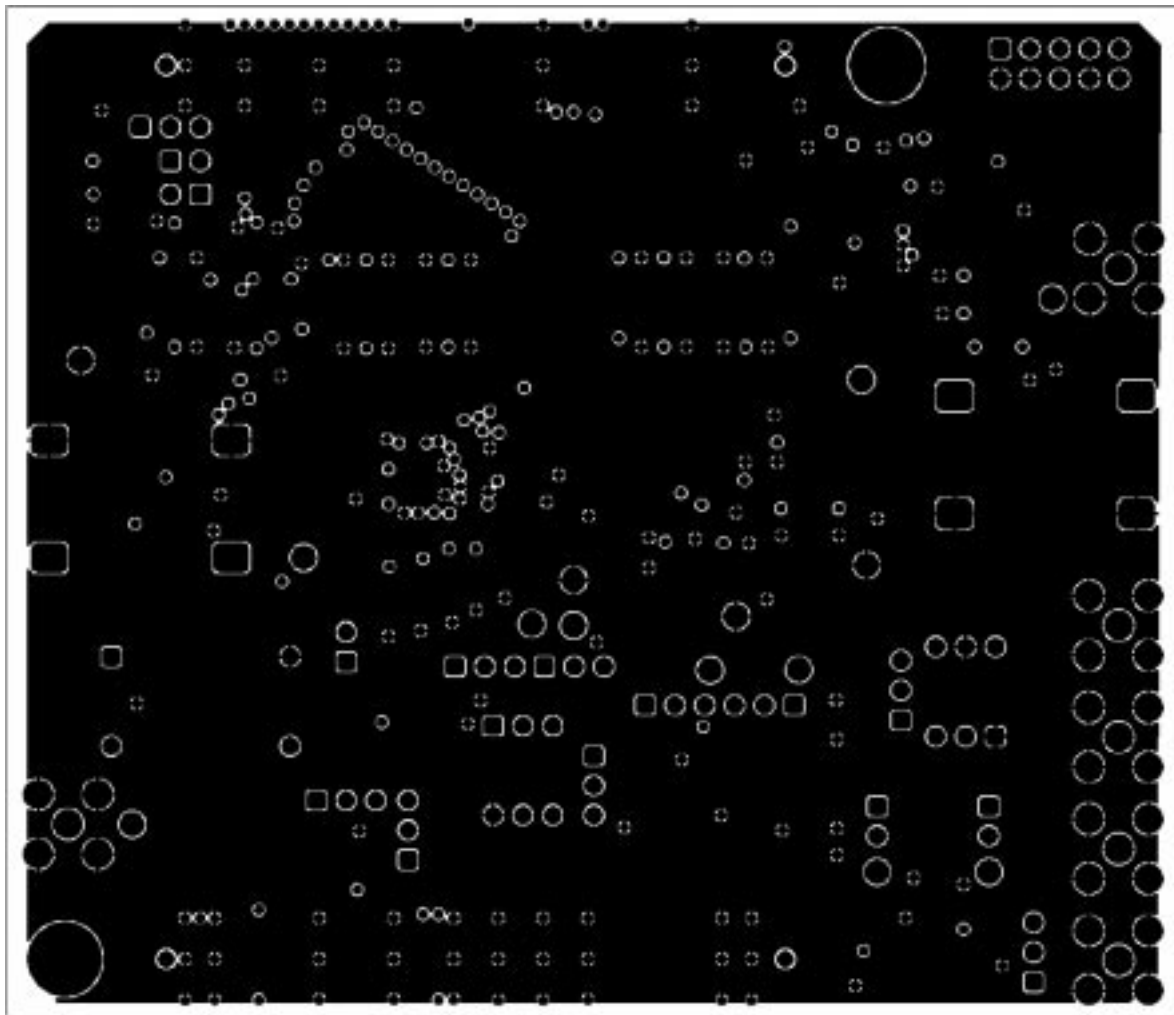
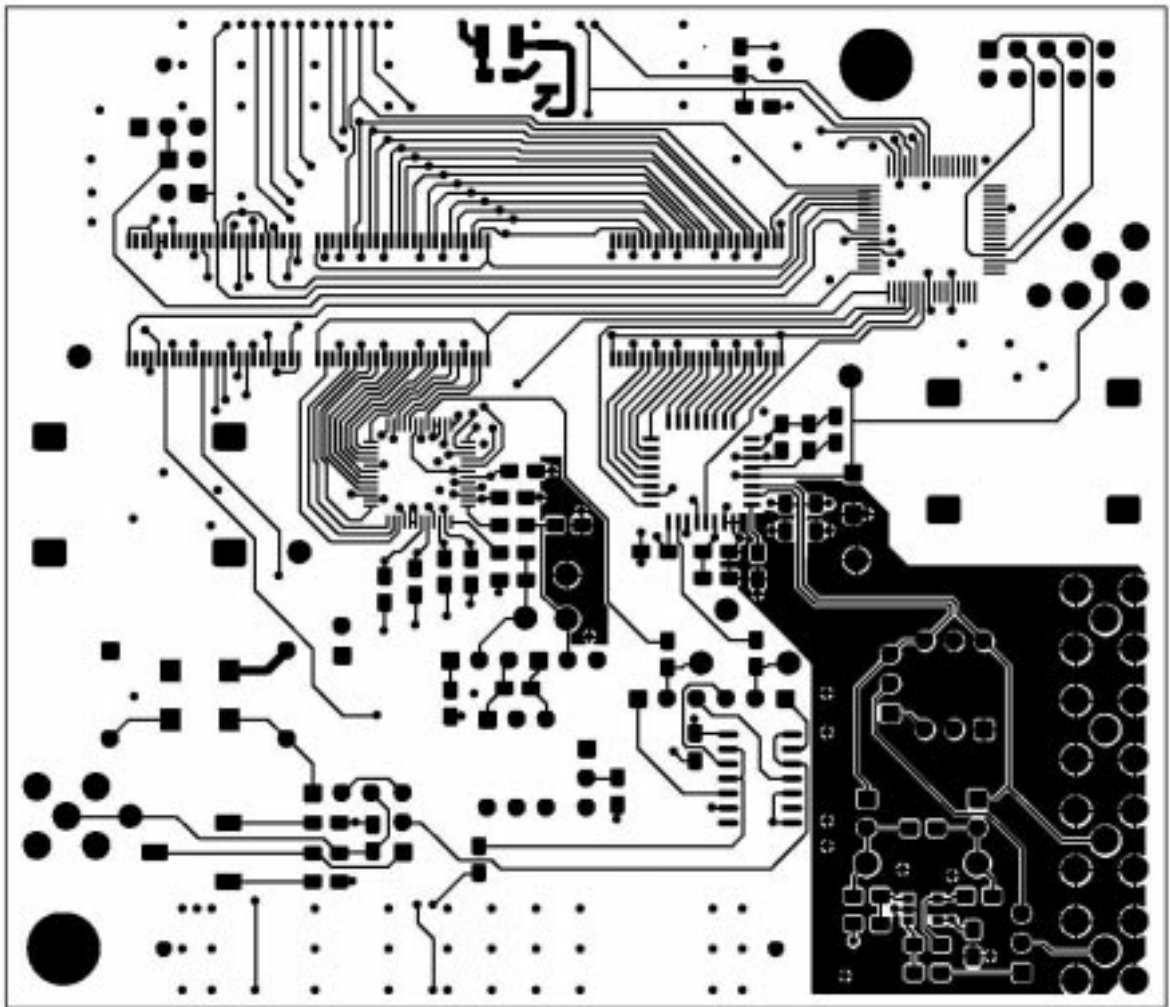


Figure 2–6. Bottom Layer



2.2 Parts List

Table 2–1 lists the parts used in constructing the EVM.

Table 2–1. Parts List

Qty	Reference Description	Description	Manufacturer	Part Number
2	U3, U1	SN74ALB16244DL bus driver	TI	SN74ALB16244DL
1	U2	SN74ALB16245DL bus transceiver	TI	SN74ALB16245DL
6	C13, C15, C26, C28, C50, C30	10- μ F 10-V case A SMD tantalum capacitor	AVX	TAJA106K010R
1	C17	1- μ F 1206 SMD ceramic capacitor 16-V X7R	AVX	1206YC105K2800J
40	C1, C2, C3, C4, C5, C6, C7, C8, C9, C10, C11, C12, C14, C16, C18, C19, C21, C22, C23, C24, C25, C27, C29, C32, C34, C35, C36, C37, C38, C39, C40, C43, C45, C47, C51, C55, C56, C57, C58, C59	0.1- μ F 0805 SMD ceramic capacitor X7R	TDK	CC0805HX7R104KTR
6	C20, C31, C33, C42, C44, C46	470-pF 0805 SMD ceramic capacitor NPO	AVX	08051A471JAT00J
2	C48, C49	22-pF 0805 SMD ceramic capacitor NPO	AVX	08051A220JAT2A
3	C52, C53, C54	UNPOP		
3	C60, C61, C62	0.01- μ F 0805 SMD ceramic capacitor X7R	TDK	CC0805HX7R103KTR
6	J3, J4, J6, J9, J10, J11	SMB connector right angle PCB	MACOM	B65N10G999X99
1	J5	0.1" spacing 2X5 header straight	Elco	008380010000010
1	U7	SN74AHC14D hex inverter	TI	SN74AHC14D
5	H1, H2, H12, H13, H14	0.1" spacing 1X2 header straight	Harwin	M20–9990206
10	H3, H4, H5, H6, H7, H8, H9, H10, H11, H15	0.1" spacing 1X3 header straight	Harwin	M20–9990306
3	L1, L2, L3	0R 1206 thick-film resistor	Multicomp	RMC18W(1206)5%0R0
1	U8	MAX4212EUK 3.3-V operational amplifier	Maxim	MAX4212EUK
1	U6	8-MHz 14-pin DIL 3.3V oscillator 100 ppm	Golledge	GXO–U102F 8 MHz
1	U10	8.0-MHz SMD 3.3V oscillator 100 ppm	Golledge	GXO–U108L 8 MHz
2	J12, J13	4-mm PCB socket black	Deltron	571–0100
2	J7, J8	4-mm PCB socket red	Deltron	571–0500
1	P1	2-k Ω 3269P potentiometer	Bourns	3269P1202

Table 2–1. Parts List (Continued)

Qty	Reference Description	Description	Manufacturer	Part Number
8	R1, R2, R4, R7, R9, R10, R14	10-k Ω 0805 thick-film resistor 1%	Multicomp	RMC110W(O8O5)1%10K
3	R5, R6, R8	510R 0805 thick-film resistor 1%	Multicomp	RMC110W(O8O5)5%510R
2	R15, R16	39R 0805 thick-film resistor 1%	Multicomp	RMC110W(O8O5)1%39R
2	R22, R23	150R 0805 thick-film resistor 1%	Multicomp	RMC110W(O8O5)1%150R
1	R24	750R 0805 thick-film resistor 1%	Rohm	MCR10EZHF7500
3	R13, R29, R30	0R 0805 thick-film resistor 1%	Multicomp	RMC110W(O8O5)5%0R0
1	R3	1K 0805 thick-film resistor 1%	Multicomp	RMC110W(O8O5)1%1K
1	R17, R20, R21, R27, R28, R31, R32	49R9 0805 SMD chip resistor 1%	Rohm	MCR10EZHF49R9
1	R12	UNPOP		
2	R18, R19	5K1 0805 thick-film resistor 1%	Multicomp	RMC110W(O8O5)5%5K1
1	R26	2-k Ω 0805 thick-film resistor 1%	Rohm	MCR10EZHF2001
4	TP3, TP4, TP13, TP14	1.32-mm test pin black	W Hughes	100–103
10	TP1, TP2, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12	1.32-mm test pin red	W Hughes	100–107
2	J1, J2	0.05" TFM-series 80-pin TH connector	Samtec	TFM–140–31–S–D–LC
1	U4	THS14XX ADC	TI	THS14XXPFB
1	U5	THS56XX DAC	TI	THS56XXVF
2	T2, T1	TT1–6–KK81 RF transformer	Mini Circuits	TT1–6–KK81
1	U9	XC9536XL–5VQ64C CPLD	Xilinx	XC9536XL–5VQ64C

The following components have been left unpopulated in this implementation: C1, C2, C3, C4, C17, C18, C19, C20, C31, C32, C33, C34, C35, C48, C49, C52, C53, C54, C56, H1, H2, H4, H10, H11, J4, J6, J9, R12, R14, R16, R20, R21, R22, R23, R24, R26, R32, T1, TP6, TP9, TP10, TP12, U1, U5, U8, U10.



Circuit Description

This chapter contains the EVM schematic diagram and discusses the various functions on the EVM.

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3.2 Address Decode and Control Logic Listing	3-7
3.3 Schematic Diagram	3-11

3.1 Circuit Function

The following paragraphs describe the function of the individual circuits. Refer to the relevant data sheet for device operating characteristics.

3.1.1 Inputs and Outputs

The ADC has differential analog inputs. These are provided via SMB connectors J10 and J11 on the EVM, and can be configured in two ways:

- For true differential input, the positive differential signal is connected to J10 and the negative differential signal is connected to J11. The jumpers on the board are then configured as: H7 (1–2), H8 (2–3), and H9 (1–2). The inputs have 50- Ω terminators.
- For single-ended input, a positive signal is applied to connector J10. The jumpers on the board are then configured as: H7 (2–3), H8 (1–2), and H9 (2–3). Transformer T2 performs the single-ended to differential signal conversion. In this mode, the 50- Ω terminators R27 and R28 perform impedance matching to attain the best distortion performance, but the signal source must be able to drive the 25- Ω load. A 50- Ω source can be used if R27 is removed from the board, with a resulting marginal increase in distortion.

SMB connector J3 can be used to input a clock signal to the board from an external source. If the source is not at the correct dc level required to input to the 74AHC14 hex inverter IC (U7), then it can be ac-coupled through C21, with the dc level trimmed using potentiometer P1 if necessary.

The EVM is designed to comply with the TI TMS320C6000 daughtercard specification. The pinout used is listed in Tables 3–1 and 3–2. In order to make the EVM compatible with both the TMS320C6XXX and TMS320C5XXX motherboard design environments, the EVM chip enable is derived from the following sources:

- $\overline{\text{OUT_CE}}$ (J1 P78) for the TMS320C6XXX, by inserting a jumper link in position 2–3 of H15.
- OUT_IS (J2 P70) for the TMS320C5XXX, by inserting a jumper link in position 1–2 of H15.

For further explanation of the daughtercard connector interface, refer to the relevant motherboard user's guide or daughtercard specification.

Buffers U1, U2, and U3 are used to avoid bus contention and provide a degree of noise isolation from the DSP motherboard.

Table 3–1. Daughtercard Connector J1

J1 Pin	Name	Function	J1 Pin	Name	Function
1		NC	41	+3.3V	POWER
2		NC	42	+3.3V	POWER
3		NC	43		NC
4		NC	44		NC
5		NC	45		NC
6		NC	46		NC
7		NC	47		NC
8		NC	48		NC
9		NC	49		NC
10		NC	50		NC
11	GND	GND	51	GND	GND
12	GND	GND	52	GND	GND
13		NC	53	BIDIR_ED15	DATA
14		NC	54	BIDIR_ED14	DATA
15		NC	55	BIDIR_ED13	DATA
16		NC	56	BIDIR_ED12	DATA
17		NC	57	BIDIR_ED11	DATA
18		NC	58	BIDIR_ED10	DATA
19		NC	59	BIDIR_ED9	DATA
20	OUT_EA6	Address	60	BIDIR_ED8	DATA
21		NC	61	GND	GND
22		NC	62	GND	GND
23	OUT_EA5	Address	63	BIDIR_ED7	DATA
24	OUT_EA4	Address	64	BIDIR_ED6	DATA
25	OUT_EA3	Address	65	BIDIR_ED5	DATA
26	OUT_EA2	Address	66	BIDIR_ED4	DATA
27		NC	67	BIDIR_ED3	DATA
28		NC	68	BIDIR_ED2	DATA
29		NC	69	BIDIR_ED1	DATA
30		NC	70	BIDIR_ED0	DATA
31	GND	GND	71	GND	GND
32	GND	GND	72	GND	GND
33		NC	73	$\overline{\text{OUT_ARE}}$	READ STROBE
34		NC	74	$\overline{\text{OUT_AWE}}$	WRITE STROBE
35		NC	75		NC
36		NC	76		NC
37		NC	77		NC
38		NC	78	$\overline{\text{OUT_CE_6}}$	CHIP ENABLE
39		NC	79	GND	GND
40		NC	80	GND	GND

Table 3–2. Daughtercard Connector J2

J2 Pin	Name	Function	J2 Pin	Name	Function
1		NC	41		NC
2		NC	42		NC
3	GND	GND	43	GND	GND
4	GND	GND	44	GND	GND
5		NC	45	OUT_TOUT	TIMER INPUT
6		NC	46	IN_TINP	TIMER OUTPUT
7	GND	GND	47		NC
8	GND	GND	48		NC
9		NC	49		NC
10		NC	50		NC
11		NC	51	GND	GND
12		NC	52	GND	GND
13		NC	53	IN_EXT_INT	INTERRUPT
14		NC	54		NC
15		NC	55		NC
16		NC	56		NC
17		NC	57		NC
18		NC	58		NC
19		NC	59		NC
20		NC	60		NC
21		NC	61	GND	GND
22		NC	62	GND	GND
23		NC	63		NC
24		NC	64		NC
25	GND	GND	65		NC
26	GND	GND	66		NC
27		NC	67		NC
28		NC	68		NC
29		NC	69		NC
30		NC	70	OUT_IS	CHIP ENABLE
31	GND	GND	71		NC
32	GND	GND	72		NC
33		NC	73		NC
34		NC	74		NC
35		NC	75	GND	GND
36		NC	76	GND	GND
37	GND	GND	77		GND
38	GND	GND	78		NC
39		NC	79	GND	GND
40		NC	80	GND	GND

3.1.2 Clock Options

The EVM provides flexibility for the source of the ADC's conversion clock. This clock can come from an external source as previously described, from a standard DIL14 HCMOS crystal oscillator module populating U6, or from a U108-style surface-mount oscillator populating U10.

Note:

Ensure that the crystal oscillator module selected can operate at the +3.3-V supply voltage.

Supplying the ADC clock using a timer output (OUT_TOUT J2 P45) is an option provided for applications that require synchronization of the ADC conversion to the DSP on the motherboard. This is selected using a jumper link on H6 (1–2).

A summary of the jumper link settings required for the various clock options is shown in Table 3–3.

Table 3–3. Jumper Settings for Clock Options

Clock Options	Onboard Oscillator	External AC Coupled Via J3	External DC Coupled Via J3	DSP Timer Via OUT_TOUT
H 3	1–2	–	2–3	–
H 5	2–3	1–2	2–3	–
H 6	2–3	2–3	2–3	1–2

3.1.3 References

The EVM relies on the THS1408 ADC using its on-chip reference.

3.1.4 Power

Power is supplied to the EVM via 4-mm banana sockets and the daughtercard connectors. This provides flexibility and a trade-off between convenience and performance as follows:

- For best performance: Use a separate low-noise analog power supply connected to J7 (+3.3 V) and J12 (GND). Use the digital supply from the daughtercard connectors.
- For good performance: Use the daughtercard connectors for both analog and digital supplies. This is achieved by inserting a jumper link in H14 on the EVM.
- For stand-alone operation: Use a separate low-noise analog power supply connected to J7 (+3.3 V) and J12 (GND) and a separate low-noise digital power supply connected to J8 (+3.3 V) and J13 (GND).

3.1.5 Interrupts

The ADC produces two signals that can be used to interrupt a DSP:

- INT: This is routed via buffer U3 to the IN_EXT_INT pin on the daughter-card connector.

Note:

This function is only supported on certain members of the THS14XX family. Refer to the device datasheet.

- FOVL: This is routed via buffer U3 to both BIDIR_ED14 and IN_TINP. This gives the DSP code developer flexibility on using the signal in their system.

3.1.6 Hardware Loopback

The EVM can be configured via insertion of jumper links H12 and H13 to go into a hardware loopback mode. This is primarily intended so that the board can be put into an operational state when it is powered up stand-alone. The control logic for this is explained in section 3.2.8.

3.1.7 ADC Write/Read Cycle

The following daughtercard address and control lines are mapped directly to the ADC when performing a write to or a read from the device:

- OUT_EA2 is mapped to A0
- OUT_EA3 is mapped to A1
- $\overline{\text{OUT_AWE}}$ is mapped to WRB
- $\overline{\text{OUT_ARE}}$ is mapped to OEB

These, combined with the address decode logic described in section 3.2.8, allow direct control of the ADC operation via the normal write/read cycles of a DSP.

3.1.8 Address Decode Logic

The EVM uses a Xilinx XC9536 (U9) CPLD to perform address decode and control. The CPLD decodes the daughtercard address and strobe lines to control the ADC chip select and the buffer direction and output-enable states. The Abel code used to generate the logic is given in Listing 3–1.

3.2 Address Decode and Control Logic Listing

Module Address

Address Decode for THS1408/5691

This file performs the address decode and logic control for the THS1408_5691_EV1_Rev2 PCB.

The equivalent truth tables are:

Chip Select Decode

OUT_EA6	OUT_EA5	OUT_EA4	OUT_EA3	OUT_EA2	$\overline{\text{OUT_CE}}$	ADCCSB	DACCSB
1	0	0	0	0	0	0	1
1	0	0	0	1	0	0	1
1	0	0	1	0	0	0	1
1	0	0	1	1	0	0	1
1	0	1	0	0	0	1	0
1	0	1	0	1	0	1	0
1	1	0	0	0	0	0	0
All other combinations						1	1

Buffer Control Decode

Operation	ADCCSB	DACCSB	OUT_ARE	OUT_AWE	DBUFOEB	ABUFDIR	ABUFDIRB	ABUFOEB	DACMODE
Write to DAC	1	0	1	0	0	1	1	1	1
Write to ADC	0	1	1	0	1	0	1	0	1
Read from ADC	0	1	0	1	1	1	0	0	1
Loop back	0	0	0	1	0	1	0	0	0
All other combinations					1	1	1	1	1

Note: Bit 13 of the data bus to the DAC is inverted when in loopback mode to account for the DAC powering up in 2s-complement input mode while the ADC powers up in binary mode.

Inputs

OUT_EA2 pin; Address bit from DSP board

OUT_EA3 pin; Address bit from DSP board

OUT_EA4 pin; Address bit from DSP board

OUT_EA5 pin; Address bit from DSP board

OUT_EA6 pin; Address bit from DSP board
 BIDIR_ED13 pin; Data bit 13
 $\overline{\text{OUT_AWE}}$ pin; DSP write enable
 OUT_ARE pin; DSP read enable
 OUT_CE pin; DSP chip enable

Outputs

DBUFOEB pin istype 'com'; DAC buffers 3-state control
 ABUFDIR pin istype 'com'; ADC buffer direction control
 ABUFDIRB pin istype 'com'; ADC FOVL flag buffer 3-state control
 ABUFOEB pin istype 'com'; ADC data bus buffer 3-state control
 DACMODE pin istype 'com'; DAC mode
 Mod_ED13 pin istype 'com'; Selectively invert BIDIR_ED13 for loop-back
 ADCCSB pin istype 'com'; Chip select for ADC

Equations

```
!ADCCSB = (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE);
!DACCSB = (OUT_EA6 and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE);
!DBUFOEB = (ADCCSB and !DACCSB and OUT_ARE and !OUT_AWE)
# (!ADCCSB and !DACCSB and !OUT_ARE and OUT_AWE); Done in longhand so signal path is only once
through device
!DBUFOEB = (!((OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and ((OUT_EA6
and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and OUT_ARE and
!OUT_AWE)
# (((OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and ((OUT_EA6
and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)
```



```
# (OUT_EA6 and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and !OUT_ARE
  and OUT_AWE);
!DACMODE = (!ADCCSB and !DACCSB and !OUT_ARE and OUT_AWE); Done in longhand so signal path is
  only once through device
!DACMODE = (((OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and OUT_EA2 and !OUT_CE)# (OUT_EA6 and
  OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and ((OUT_EA6 and !OUT_EA5
  and OUT_EA4 and !OUT_EA3 & !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and !OUT_ARE
  and OUT_AWE);Mod_ED13 = (!BIDIR_ED13 and ((OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3
  and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and ((OUT_EA6
  and !OUT_EA5 and OUT_EA4 and !OUT_EA3 & !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and !OUT_ARE
  and OUT_AWE)
# (BIDIR_ED13 and !(((OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and
  !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and !OUT_EA4 and OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and ((OUT_EA6
  and !OUT_EA5 and OUT_EA4 and !OUT_EA3 & !OUT_EA2 and !OUT_CE)
# (OUT_EA6 and !OUT_EA5 and OUT_EA4 and !OUT_EA3 and OUT_EA2 and !OUT_CE)
# (OUT_EA6 and OUT_EA5 and !OUT_EA4 and !OUT_EA3 and !OUT_EA2 and !OUT_CE)) and !OUT_ARE
  and OUT_AWE));
```

END

3.3 Schematic Diagrams

This section contains the schematic diagrams for the EVM.